

Product Information



100µm black low temperature reactive HAF mounting tape

Product Description

tesa® Low Temperature Reactive (LTR) 58484 is a reactive mounting tape activated at moderate temperatures. This black double-sided tape has no backing. It is protected by a PE-coated paper liner.

tesa® LTR 58484 is free of halogen and compliant with current RoHS directive.

At room temperature tesa® LTR 58484 is not tacky. It is activated by moderate heat and pressure applied during the assembly process.

Special Features:

- · Extremely high bonding performance and reliability, even on slim bonding areas and thin design gaps
- · Activated at low temperature and pressure
- · Excellent shock resistance
- Sebum resistant
- · Very low oozing ratio

Application Fields

tesa® LTR 58484 is especially recommended for structural bonding of temperature sensitive substrates:

- * Bonding of anodized aluminium
- * Bonding of plastics
- * Mounting of sensitive electronic parts

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

Product Construction

Type of liner
 PE-coated paper,
 poly-coated paper
 Color
 black, beige

Backing material none

• Type of adhesive low temperature

activated reactive

adhesive



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	Bonding strength (push-out)	6.5 N/mm ²	 Low VOC 	very good
•	Donaing strength (pash-out)	0.5 (4/111111	V LOVV VOC	very good

Additional Information

Technical recommendations:

tesa® LTR 58484 is not self adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

1. Pre-lamination:

During pre-lamination, laminate the adhesive tape onto the first component.

Machine setting:

- * Temperature¹ 50-60 °C
- * Pressure² 1 3 bar
- * Time 5 20 s

Short-time exposure to 60°C bond line temperature during pre-lamination does not impact final bonding potential.

2. Bonding:

Remove the liner from tape after the pre-lamination step.

Position the second component. Apply temperature and pressure for the bonding time to reach sufficient bonding strength.



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*	Temperature ¹	75	-	110	°C

* Pressure² 2 – 4 bar

* Time 10 - 480 s

Setting:

Short cycle times can be achieved at 110 °C bond line temperature. For activation at lower temperatures, increase the heat-press time or combine a short heat-press step with oven curing.

To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours.

Bonding strength values were obtained under standard laboratory conditions (Material: PC/PC; bonding conditions: temperature (jig) = $90 \, ^{\circ}$ C; pressure = $5 \, \text{bar}$; time = $120 \, \text{sec}$).

Storage:

tesa recommends storage in original packaging in cool and dry conditions.

Low Temperature Reactive should not be exposed to more than 35°C before bonding (during transport, storage and converting).

The shelf life is 15 months after coating date. For the actual shelf life please refer to the best before date on the label in the log roll core.



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¹ 'Pre-lamination'	' and 'Bondin	a' temperature	refer to the	data that is	measured in the	hond line
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Disclaimer

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² 'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.